

WHAT IS CLAIMED IS:

1. A lead frame plating apparatus for injecting plating solution through nozzles to a lead frame with a uniform distribution of the plating solution, the apparatus comprising:
 - 5 side inlets provided in the diagonal direction at opposite sides of the lead frame plating apparatus, respectively, for supplying the plating solution;
a flow mixing room defined with an inner space in the longitudinal direction for the plating solutions, having flowed in through the side inlets, to be mixed with each other while flowing in parallel; and
 - 10 a plating solution outlet for guiding the plating solution in the direction of nozzles, the plating solution outlet having a cross sectional area smaller than that of the flow mixing room.
2. The apparatus as set forth in claim 1, wherein the plating solution outlet is installed with a distributing plate provided with a plurality of holes.
- 15 3. The apparatus as set forth in claim 1 or 2, the apparatus further comprising:
 - a plating solution distribution part provided with the nozzles at an upper side of the plating solution outlet, each nozzle being provided, at the lower end thereof, with a divergent-shaped expansion tube such that an inner
 - 20 diameter of the inlet of the expansion tube, larger than that of the nozzle, gradually decreased to the extent of the inner diameter of the nozzle.
4. The apparatus as set forth in claim 3, wherein the expansion tube at the lower end of the nozzle is mounted by being inserted into the inside of the plating solution distribution part.
- 25 5. The apparatus as set forth in claim 3, wherein the expansion tube at the lower end of the nozzle is mounted in a state of being protruded from an outer side of the plating solution distribution part.